

SAW FILTER FOR PAGER



FEATURES

- Compact Size
- Metal Package Type(F11)
- Surface Mounted Device Type(SC54)

APPLICATION

- Saw Filter For Pager and FRS

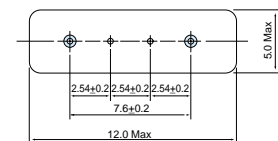
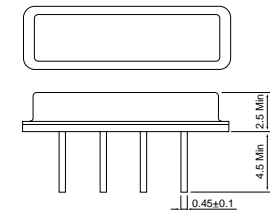
SPECIFICATIONS

	S1□□P	S169P	S235P, S358P
Nominal Center Frequency(fo)	139,147,150,155 163,171 MHz	169.6 MHz	235.3375, 358.5375 MHz
Passband Width	fo ±4.0 MHz	fo ±2.0 MHz	fo ±0.5 MHz
Insertion Loss	6.5 dB Max.	6.0 dB Max.	4.0 dB Max.
Passband Ripple	2.0 dB Max.	3.0 dB Max.	
Terminating Impedance(Zo)	210 Ω // Tuning	210 Ω // Tuning	150 Ω // 0pF
Package Type	F11 or SC54	F11 or SC54	F11 or SC54

	S219P	S222P	S299P
Nominal Center Frequency(fo)	219.5 MHz	222 MHz	299 MHz
Passband Width	fo ±615 KHz	fo ±2.0 MHz	fo ±3.0 MHz
Insertion Loss	3.5 dB Max.	4.5 dB Max.	4.0 dB Max.
Passband Ripple	2.0 dB Max.	2.0 dB Max.	1.5 dB Max.
Terminating Impedance(Zo)	210 Ω // 0pF	150 Ω // 0pF	150 Ω // 0pF
Package Type	F11 or SC75	F11 or SC54	F11 or SC54

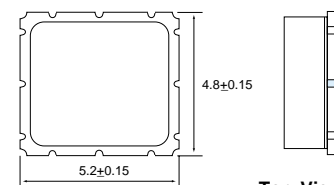
	S281P, S284P	S282P	S323P, S326P
Nominal Center Frequency(fo)	281,284 MHz	282 MHz	323.65, 326.95 MHz
Passband Width	fo ±3.0 MHz	fo ±4.0 MHz	fo ±1.65 MHz
Insertion Loss	4.5 dB Max.	4.5 dB Max.	2.5 dB Max.
Passband Ripple	2.0 dB Max.	2.5 dB Max.	
Terminating Impedance(Zo)	150 Ω // 0pF	150 Ω // 0pF	150 Ω // 0pF
Package Type	F11 or SC54	F11 or SC54	F11 or SC54

	S325P	S□□□P	S930P, S930J
Nominal Center Frequency(fo)	325.3 MHz	402,406,410,414, 418,422,426,430, 434,438,442,446, 450,454,458,462, 465,466,470,474, 478,482,486,490, 494,498,502,506, 510,514,518 MHz	930.5 MHz
Passband Width	fo ±3.3 MHz	fo ±2.0 MHz	fo ±2.0 MHz
Insertion Loss	4.0 dB Max.	4.5 dB Max.	4.5 dB Max.
Passband Ripple	2.0 dB Max.	2.0 dB Max.	
Terminating Impedance(Zo)	150 Ω // 0pF	150 Ω // 0pF	50 Ω +SeriesL(10nH): S930P 50 Ω (QpF): S930J
Package Type	F11 or SC54	F11 or SC54	F11 or SC54



F11 Type

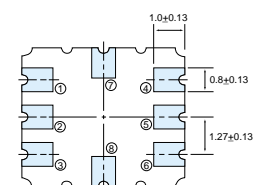
[Unit:mm]



Top View



Side View



Bottom View

PIN NO.	FUNCTION
①③④⑥	GROUND
②	SIGNAL
⑤	SIGNAL
⑦⑧	GROUND

Package Material: 96% White Alumina
Lid Material: 92% Black Alumina
Lid Seal: Epoxy, 0.25mm Seal Width
Solder Pad:
Ag Based Thick Flim
Electroless Ni plating 5 μ m
Gold Plating 0.5 μ m Min.